



Module 19

Quiz: Bluetooth Low Energy



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Q1 Definitions

In 16 words or less, define this terms.

Part a) Profile.

Part b) Service.

Part c) Characteristic.

Q2 Definitions

In 16 words or less, define this terms.

Part a) Client.

Part b) Server.

Part c) Advertising.

Q3 Low power

Explain three mechanisms that BLE uses to operate at low power.

Q4 UART

UART is used to communicate between the CC2650 and the MSP432. The channel uses a full-duplex UART port. Can data transfer in both directions at the same time?

Q5 Physical Layer

In what form is data encoded as it travels from transmitter to receiver?

Q6 Medium

How do we classify the medium used for Bluetooth Communication? Is it unguided, lossless, or guided?

Q7 Error detection

Part a) What mechanism does the SAP-SNP protocol use to detect errors? How is the error checking generated on the transmitter?

Part b) How is the received message checked for errors?

Q8 Radio

At what frequency does the Bluetooth radio communicate?

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